

**CHIP STRUCTURE WITH PADS HAVING BUMPS OR WIREBONDED WIRES
FORMED THEREOVER OR USED TO BE TESTED THERETO**

Appl. No. : 10/730,834 Confirmation No. 5204
Applicant : Nick Kuo,
Chiu-Ming Chou,
Chien-Kang Chou,
Chu-Fu Lin
Filed : December 8, 2003
TC/A.U. : 2826
Examiner : ANDUJAR, LEONARDO
Docket No. : MEGP0033USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT AND RESPONSE TO NON-FINAL OFFICE ACTION

5 Sir:

In response to the Non-Final Office Action mailed May 7, 2007, please amend the above-identified application and consider the remarks as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

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Remarks/Arguments begin on page 9 of this paper.